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High-Performance 8-bit CMOS EPROM Microcontrollers with 10-bit A/D

Microcontroller Core Features:

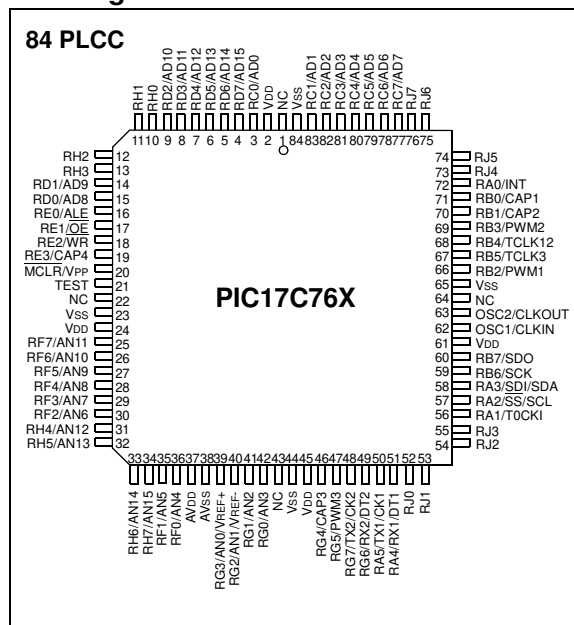
- Only 58 single word instructions to learn
- All single cycle instructions (121 ns), except for program branches and table reads/writes which are two-cycle
- Operating speed:
 - DC - 33 MHz clock input
 - DC - 121 ns instruction cycle
- 8 x 8 Single-Cycle Hardware Multiplier
- Interrupt capability
- 16 level deep hardware stack
- Direct, indirect, and relative addressing modes
- Internal/external program memory execution, capable of addressing 64 K x 16 program memory space

Device	Memory	
	Program (x16)	Data (x8)
PIC17C752	8 K	678
PIC17C756A	16 K	902
PIC17C762	8 K	678
PIC17C766	16 K	902

Peripheral Features:

- Up to 66 I/O pins with individual direction control
- 10-bit, multi-channel Analog-to-Digital converter
- High current sink/source for direct LED drive
- Four capture input pins
 - Captures are 16-bit, max resolution 121 ns
- Three PWM outputs (resolution is 1 to 10-bits)
- TMR0: 16-bit timer/counter with 8-bit programmable prescaler
- TMR1: 8-bit timer/counter
- TMR2: 8-bit timer/counter
- TMR3: 16-bit timer/counter
- Two Universal Synchronous Asynchronous Receiver Transmitters (USART/SCI) with independent baud rate generators
- Synchronous Serial Port (SSP) with SPI™ and I²C™ modes (including I²C Master mode)

Pin Diagrams



Special Microcontroller Features:

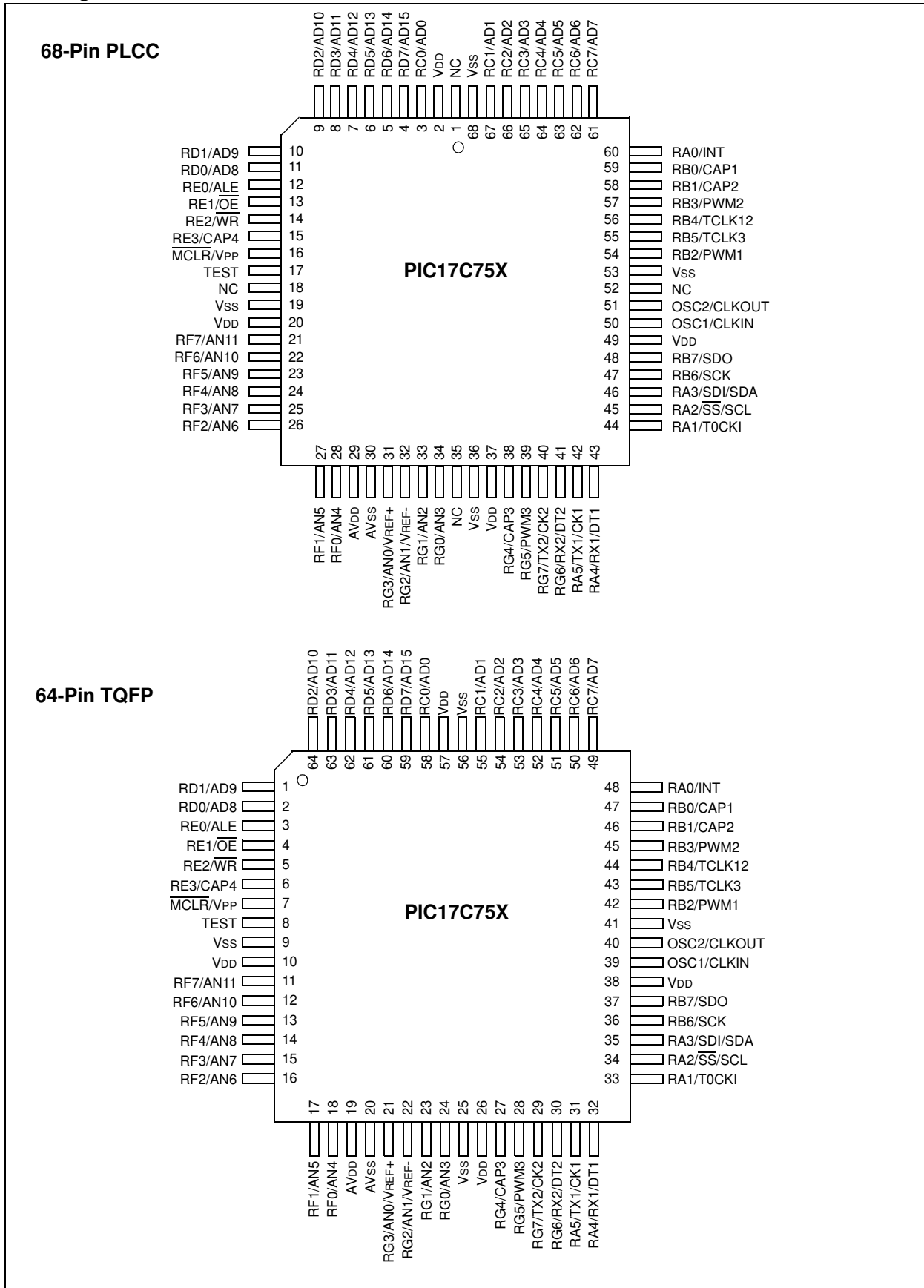
- Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- Brown-out Reset
- Code protection
- Power saving SLEEP mode
- Selectable oscillator options

CMOS Technology:

- Low power, high speed CMOS EPROM technology
- Fully static design
- Wide operating voltage range (3.0V to 5.5V)
- Commercial and Industrial temperature ranges
- Low power consumption
 - < 5 mA @ 5V, 4 MHz
 - 100 μA typical @ 4.5V, 32 kHz
 - < 1 μA typical standby current @ 5V

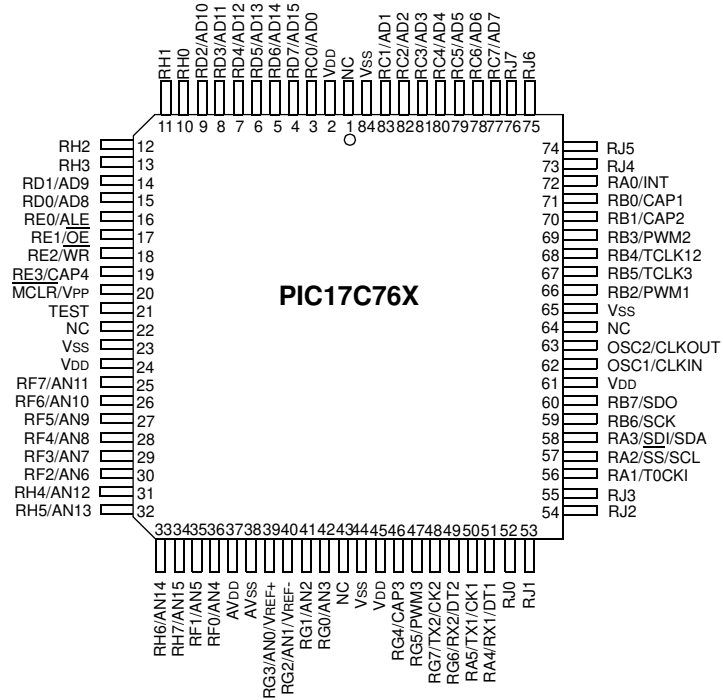
PIC17C7XX

Pin Diagrams cont.'d

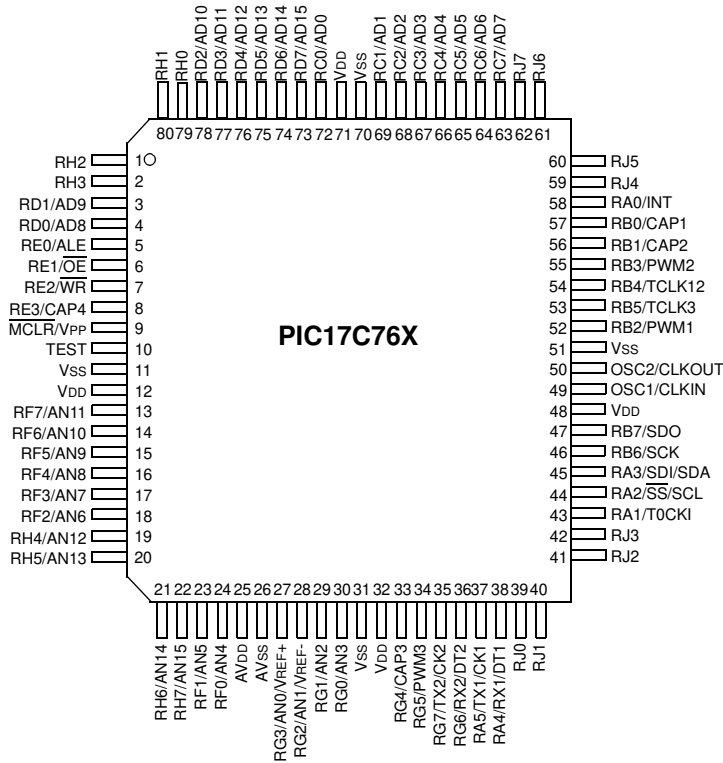


Pin Diagrams cont.'d

84-pin PLCC



80-Pin TQFP



PIC17C7XX

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PIC17C7XX

NOTES:

1.0 OVERVIEW

This data sheet covers the PIC17C7XX group of the PIC17CXXX family of microcontrollers. The following devices are discussed in this data sheet:

- PIC17C752
- PIC17C756A
- PIC17C762
- PIC17C766

The PIC17C7XX devices are 68/84-pin, EPROM based members of the versatile PIC17CXXX family of low cost, high performance, CMOS, fully static, 8-bit microcontrollers.

All PIC[®] microcontrollers employ an advanced RISC architecture. The PIC17CXXX has enhanced core features, 16-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 16-bit wide instruction word with a separate 8-bit wide data path. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 58 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance. For mathematical intensive applications, all devices have a single cycle 8 x 8 Hardware Multiplier.

PIC17CXXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

PIC17C7XX devices have up to 902 bytes of RAM and 66 I/O pins. In addition, the PIC17C7XX adds several peripheral features, useful in many high performance applications, including:

- Four timer/counters
- Four capture inputs
- Three PWM outputs
- Two independent Universal Synchronous Asynchronous Receiver Transmitters (USARTs)
- An A/D converter (multi-channel, 10-bit resolution)
- A Synchronous Serial Port (SPI and I²C w/ Master mode)

These special features reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption.

There are four oscillator options, of which the single pin RC oscillator provides a low cost solution, the LF oscillator is for low frequency crystals and minimizes power consumption, XT is a standard crystal and the EC is for external clock input.

The SLEEP (power-down) mode offers additional power saving. Wake-up from SLEEP can occur through several external and internal interrupts and device RESETS.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software malfunction.

There are four configuration options for the device operational mode:

- Microprocessor
- Microcontroller
- Extended microcontroller
- Protected microcontroller

The microprocessor and extended microcontroller modes allow up to 64K-words of external program memory.

The device also has Brown-out Reset circuitry. This allows a device RESET to occur if the device VDD falls below the Brown-out voltage trip point (BVDD). The chip will remain in Brown-out Reset until VDD rises above BVDD.

A UV erasable, CERQUAD packaged version (compatible with PLCC), is ideal for code development, while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC17C7XX fits perfectly in applications that require extremely fast execution of complex software programs. These include applications ranging from precise motor control and industrial process control to automotive, instrumentation, and telecom applications.

The EPROM technology makes customization of application programs (with unique security codes, combinations, model numbers, parameter storage, etc.) fast and convenient. Small footprint package options (including die sales) make the PIC17C7XX ideal for applications with space limitations that require high performance.

High speed execution, powerful peripheral features, flexible I/O, and low power consumption all at low cost make the PIC17C7XX ideal for a wide range of embedded control applications.

1.1 Family and Upward Compatibility

The PIC17CXXX family of microcontrollers have architectural enhancements over the PIC16C5X and PIC16CXX families. These enhancements allow the device to be more efficient in software and hardware requirements. Refer to Appendix A for a detailed list of enhancements and modifications. Code written for PIC16C5X or PIC16CXX can be easily ported to PIC17CXXX devices (Appendix B).

1.2 Development Support

The PIC17CXXX family is supported by a full featured macro assembler, a software simulator, an in-circuit emulator, a universal programmer, a "C" compiler and fuzzy logic support tools. For additional information, see Section 19.0.

PIC17C7XX

TABLE 1-1: PIC17CXXX FAMILY OF DEVICES

Features		PIC17C42A	PIC17C43	PIC17C44	PIC17C752	PIC17C756A	PIC17C762	PIC17C766
Maximum Frequency of Operation		33 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz
Operating Voltage Range		2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V	3.0 - 5.5V	3.0 - 5.5V	3.0 - 5.5V	3.0 - 5.5V
Program Memory (x16)	(EPROM)	2 K	4 K	8 K	8 K	16 K	8 K	16 K
	(ROM)	—	—	—	—	—	—	—
Data Memory (bytes)		232	454	454	678	902	678	902
Hardware Multiplier (8 x 8)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer0 (16-bit + 8-bit postscaler)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer1 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer2 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Timer3 (16-bit)		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Capture inputs (16-bit)		2	2	2	4	4	4	4
PWM outputs (up to 10-bit)		2	2	2	3	3	3	3
USART/SCI		1	1	1	2	2	2	2
A/D channels (10-bit)		—	—	—	12	12	16	16
SSP (SPI/I ² C w/Master mode)		—	—	—	Yes	Yes	Yes	Yes
Power-on Reset		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Watchdog Timer		Yes	Yes	Yes	Yes	Yes	Yes	Yes
External Interrupts		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Interrupt Sources		11	11	11	18	18	18	18
Code Protect		Yes	Yes	Yes	Yes	Yes	Yes	Yes
Brown-out Reset		—	—	—	Yes	Yes	Yes	Yes
In-Circuit Serial Programming		—	—	—	Yes	Yes	Yes	Yes
I/O Pins		33	33	33	50	50	66	66
I/O High Current Capability	Source	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA
	Sink	25 mA ⁽¹⁾	25 mA ⁽¹⁾	25 mA ⁽¹⁾	25 mA ⁽¹⁾	25 mA ⁽¹⁾	25 mA ⁽¹⁾	25 mA ⁽¹⁾
Package Types		40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	64-pin TQFP 68-pin PLCC	64-pin TQFP 68-pin PLCC	80-pin TQFP 84-pin PLCC	80-pin TQFP 84-pin PLCC

Note 1: Pins RA2 and RA3 can sink up to 60 mA.

2.0 DEVICE VARIETIES

Each device has a variety of frequency ranges and packaging options. Depending on application and production requirements, the proper device option can be selected using the information in the PIC17C7XX Product Selection System section at the end of this data sheet. When placing orders, please use the "PIC17C7XX Product Identification System" at the back of this data sheet to specify the correct part number. When discussing the functionality of the device, memory technology and voltage range does not matter.

There are two memory type options. These are specified in the middle characters of the part number.

1. **C**, as in PIC17**C**756A. These devices have EPROM type memory.
2. **CR**, as in PIC17**CR**756A. These devices have ROM type memory.

All these devices operate over the standard voltage range. Devices are also offered which operate over an extended voltage range (and reduced frequency range). Table 2-1 shows all possible memory types and voltage range designators for a particular device. These designators are in **bold** typeface.

TABLE 2-1: DEVICE MEMORY VARIETIES

Memory Type	Voltage Range	
	Standard	Extended
EPROM	PIC17 C XXX	PIC17 LC XXX
ROM	PIC17 CR XXX	PIC17 LCR XXX
Note: Not all memory technologies are available for a particular device.		

2.1 UV Erasable Devices

The UV erasable version, offered in CERQUAD package, is optimal for prototype development and pilot programs.

The UV erasable version can be erased and reprogrammed to any of the configuration modes. Third party programmers also are available; refer to the *Third Party Guide* for a list of sources.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers expecting frequent code changes and updates.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround Production (SQTPsm) Devices

Microchip offers a unique programming service, where a few user defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry code, password or ID number.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, thus giving customers a low cost option for high volume, mature products.

ROM devices do not allow serialization information in the program memory space.

For information on submitting ROM code, please contact your regional sales office.

Note: Presently, NO ROM versions of the PIC17C7XX devices are available.

PIC17C7XX

NOTES:

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC17CXXX can be attributed to a number of architectural features, commonly found in RISC microprocessors. To begin with, the PIC17CXXX uses a modified Harvard architecture. This architecture has the program and data accessed from separate memories. So, the device has a program memory bus and a data memory bus. This improves bandwidth over traditional von Neumann architecture, where program and data are fetched from the same memory (accesses over the same bus). Separating program and data memory further allows instructions to be sized differently than the 8-bit wide data word. PIC17CXXX opcodes are 16-bits wide, enabling single word instructions. The full 16-bit wide program memory bus fetches a 16-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions execute in a single cycle (121 ns @ 33 MHz), except for program branches and two special instructions that transfer data between program and data memory.

The PIC17CXXX can address up to 64K x 16 of program memory space.

The **PIC17C752** and **PIC17C762** integrate 8K x 16 of EPROM program memory on-chip.

The **PIC17C756A** and **PIC17C766** integrate 16K x 16 EPROM program memory on-chip.

A simplified block diagram is shown in Figure 3-1. The descriptions of the device pins are listed in Table 3-1.

Program execution can be internal only (Microcontroller or Protected Microcontroller mode), external only (Microprocessor mode), or both (Extended Microcontroller mode). Extended Microcontroller mode does not allow code protection.

The PIC17CXXX can directly or indirectly address its register files or data memory. All special function registers, including the Program Counter (PC) and Working Register (WREG), are mapped in data memory. The PIC17CXXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC17CXXX simple, yet efficient. In addition, the learning curve is reduced significantly.

One of the PIC17CXXX family architectural enhancements from the PIC16CXX family, allows two file registers to be used in some two operand instructions. This allows data to be moved directly between two registers without going through the WREG register, thus increasing performance and decreasing program memory usage.

The PIC17CXXX devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The WREG register is an 8-bit working register used for ALU operations.

All PIC17CXXX devices have an 8 x 8 hardware multiplier. This multiplier generates a 16-bit result in a single cycle.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), Zero (Z) and Overflow (OV) bits in the ALUSTA register. The C and DC bits operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

Signed arithmetic is comprised of a magnitude and a sign bit. The overflow bit indicates if the magnitude overflows and causes the sign bit to change state. That is, if the result of 8-bit signed operations is greater than 127 (7Fh), or less than -128 (80h).

Signed math can have greater than 7-bit values (magnitude), if more than one byte is used. The overflow bit only operates on bit6 (MSb of magnitude) and bit7 (sign bit) of each byte value in the ALU. That is, the overflow bit is not useful if trying to implement signed math where the magnitude, for example, is 11-bits.

If the signed math values are greater than 7-bits (such as 15-, 24-, or 31-bit), the algorithm must ensure that the low order bytes of the signed value ignore the overflow status bit.

Example 3-1 shows two cases of doing signed arithmetic. The Carry (C) bit and the Overflow (OV) bit are the most important status bits for signed math operations.

EXAMPLE 3-1: 8-BIT MATH ADDITION

Hex Value	Signed Values	Unsigned Values
FFh	-1	255
+ 01h	+ 1	+ 1
= 00h	= 0 (FEh)	= 256 → 00h
C bit = 1	C bit = 1	C bit = 1
OV bit = 0	OV bit = 0	OV bit = 0
DC bit = 1	DC bit = 1	DC bit = 1
Z bit = 1	Z bit = 1	Z bit = 1
Hex Value	Signed Values	Unsigned Values
7Fh	127	127
+ 01h	+ 1	+ 1
= 80h	= 128 → 00h	= 128
C bit = 0	C bit = 0	C bit = 0
OV bit = 1	OV bit = 1	OV bit = 1
DC bit = 1	DC bit = 1	DC bit = 1
Z bit = 0	Z bit = 0	Z bit = 0

PIC17C7XX

FIGURE 3-1: PIC17C752/756A BLOCK DIAGRAM

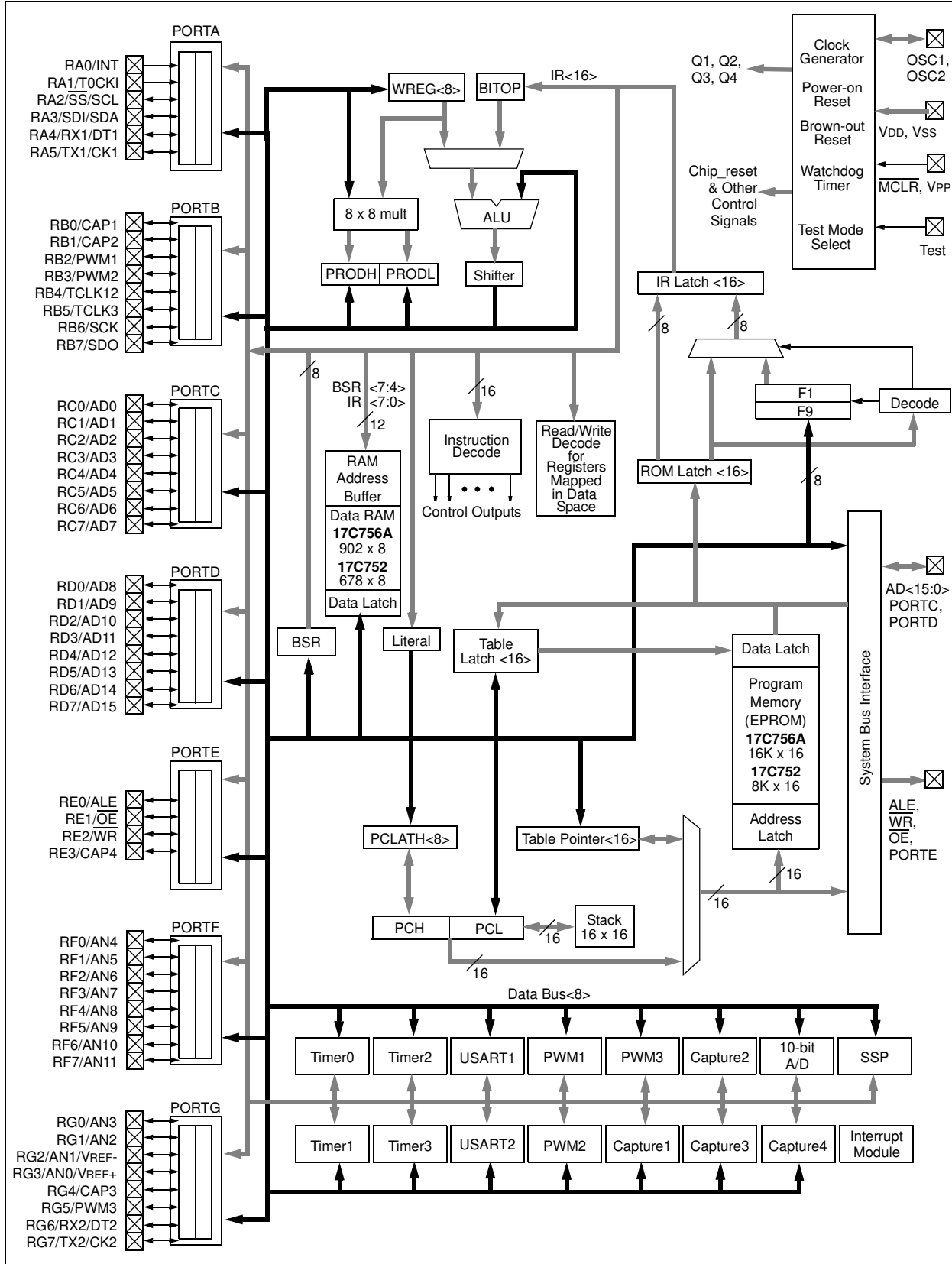
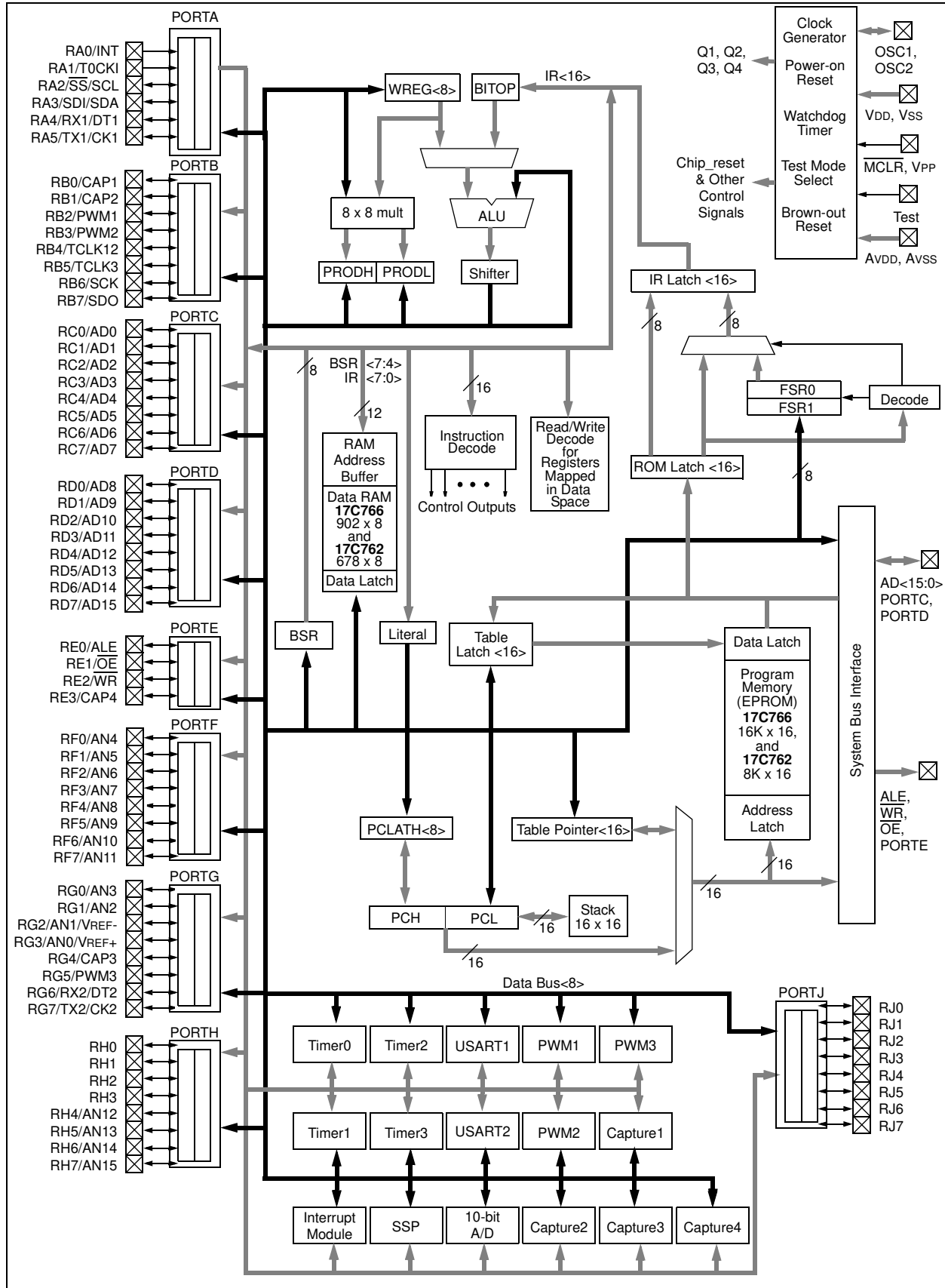


FIGURE 3-2: PIC17C762/766 BLOCK DIAGRAM



PIC17C7XX

TABLE 3-1: PINOUT DESCRIPTIONS

Name	PIC17C75X			PIC17C76X		I/O/P Type	Buffer Type	Description
	DIP No.	PLCC No.	TQFP No.	PLCC No.	QFP No.			
OSC1/CLKIN	47	50	39	62	49	I	ST	Oscillator input in Crystal/Resonator or RC Oscillator mode. External clock input in External Clock mode.
OSC2/CLKOUT	48	51	40	63	50	O	—	Oscillator output. Connects to crystal or resonator in Crystal Oscillator mode. In RC Oscillator or External Clock modes, OSC2 pin outputs CLKOUT which has one fourth the frequency (Fosc/4) of OSC1 and denotes the instruction cycle rate.
MCLR/VPP	15	16	7	20	9	I/P	ST	Master clear (RESET) input or Programming Voltage (VPP) input. This is the active low RESET input to the device.
RA0/INT	56	60	48	72	58	I	ST	<p>PORTA pins have individual differentiations that are listed in the following descriptions:</p> <p>RA0 can also be selected as an external interrupt input. Interrupt can be configured to be on positive or negative edge. Input only pin.</p> <p>RA1 can also be selected as an external interrupt input and the interrupt can be configured to be on positive or negative edge. RA1 can also be selected to be the clock input to the Timer0 timer/counter. Input only pin.</p> <p>RA2 can also be used as the slave select input for the SPI or the clock input for the I²C bus. High voltage, high current, open drain port pin.</p> <p>RA3 can also be used as the data input for the SPI or the data for the I²C bus. High voltage, high current, open drain port pin.</p> <p>RA4 can also be selected as the USART1 (SCI) Asynchronous Receive or USART1 (SCI) Synchronous Data. Output available from USART only.</p> <p>RA5 can also be selected as the USART1 (SCI) Asynchronous Transmit or USART1 (SCI) Synchronous Clock. Output available from USART only.</p>
RA1/T0CKI	41	44	33	56	43	I	ST	
RA2/ \overline{SS} /SCL	42	45	34	57	44	I/O ⁽²⁾	ST	
RA3/SDI/SDA	43	46	35	58	45	I/O ⁽²⁾	ST	
RA4/RX1/DT1	40	43	32	51	38	I/O ⁽¹⁾	ST	
RA5/TX1/CK1	39	42	31	50	37	I/O ⁽¹⁾	ST	
RB0/CAP1	55	59	47	71	57	I/O	ST	<p>PORTB is a bi-directional I/O Port with software configurable weak pull-ups.</p> <p>RB0 can also be the Capture1 input pin.</p> <p>RB1 can also be the Capture2 input pin.</p> <p>RB2 can also be the PWM1 output pin.</p> <p>RB3 can also be the PWM2 output pin.</p> <p>RB4 can also be the external clock input to Timer1 and Timer2.</p> <p>RB5 can also be the external clock input to Timer3.</p> <p>RB6 can also be used as the master/slave clock for the SPI.</p> <p>RB7 can also be used as the data output for the SPI.</p>
RB1/CAP2	54	58	46	70	56	I/O	ST	
RB2/PWM1	50	54	42	66	52	I/O	ST	
RB3/PWM2	53	57	45	69	55	I/O	ST	
RB4/TCLK12	52	56	44	68	54	I/O	ST	
RB5/TCLK3	51	55	43	67	53	I/O	ST	
RB6/SCK	44	47	36	59	46	I/O	ST	
RB7/SDO	45	48	37	60	47	I/O	ST	

Legend: I = Input only; O = Output only; I/O = Input/Output;
P = Power; — = Not Used; TTL = TTL input; ST = Schmitt Trigger input

Note 1: The output is only available by the peripheral operation.
Note 2: Open drain input/output pin. Pin forced to input upon any device RESET.

TABLE 3-1: PINOUT DESCRIPTIONS (CONTINUED)

Name	PIC17C75X			PIC17C76X		I/O/P Type	Buffer Type	Description
	DIP No.	PLCC No.	TQFP No.	PLCC No.	QFP No.			
RC0/AD0	2	3	58	3	72	I/O	TTL	PORTC is a bi-directional I/O Port. This is also the least significant byte (LSB) of the 16-bit wide system bus in Microprocessor mode or Extended Microcontroller mode. In multiplexed system bus configuration, these pins are address output as well as data input or output.
RC1/AD1	63	67	55	83	69	I/O	TTL	
RC2/AD2	62	66	54	82	68	I/O	TTL	
RC3/AD3	61	65	53	81	67	I/O	TTL	
RC4/AD4	60	64	52	80	66	I/O	TTL	
RC5/AD5	58	63	51	79	65	I/O	TTL	
RC6/AD6	58	62	50	78	64	I/O	TTL	
RC7/AD7	57	61	49	77	63	I/O	TTL	
RD0/AD8	10	11	2	15	4	I/O	TTL	PORTD is a bi-directional I/O Port. This is also the most significant byte (MSB) of the 16-bit system bus in Microprocessor mode or Extended Microcontroller mode. In multiplexed system bus configuration, these pins are address output as well as data input or output.
RD1/AD9	9	10	1	14	3	I/O	TTL	
RD2/AD10	8	9	64	9	78	I/O	TTL	
RD3/AD11	7	8	63	8	77	I/O	TTL	
RD4/AD12	6	7	62	7	76	I/O	TTL	
RD5/AD13	5	6	61	6	75	I/O	TTL	
RD6/AD14	4	5	60	5	74	I/O	TTL	
RD7/AD15	3	4	59	4	73	I/O	TTL	
RE0/ALE	11	12	3	16	5	I/O	TTL	PORTE is a bi-directional I/O Port. In Microprocessor mode or Extended Microcontroller mode, RE0 is the Address Latch Enable (ALE) output. Address should be latched on the falling edge of ALE output. In Microprocessor or Extended Microcontroller mode, RE1 is the Output Enable (\overline{OE}) control output (active low). In Microprocessor or Extended Microcontroller mode, RE2 is the Write Enable (\overline{WR}) control output (active low). RE3 can also be the Capture4 input pin.
RE1/ \overline{OE}	12	13	4	17	6	I/O	TTL	
RE2/ \overline{WR}	13	14	5	18	7	I/O	TTL	
RE3/CAP4	14	15	6	19	8	I/O	ST	
RF0/AN4	26	28	18	36	24	I/O	ST	PORTF is a bi-directional I/O Port. RF0 can also be analog input 4. RF1 can also be analog input 5. RF2 can also be analog input 6. RF3 can also be analog input 7. RF4 can also be analog input 8. RF5 can also be analog input 9. RF6 can also be analog input 10. RF7 can also be analog input 11.
RF1/AN5	25	27	17	35	23	I/O	ST	
RF2/AN6	24	26	16	30	18	I/O	ST	
RF3/AN7	23	25	15	29	17	I/O	ST	
RF4/AN8	22	24	14	28	16	I/O	ST	
RF5/AN9	21	23	13	27	15	I/O	ST	
RF6/AN10	20	22	12	26	14	I/O	ST	
RF7/AN11	19	21	11	25	13	I/O	ST	

Legend: I = Input only; O = Output only; I/O = Input/Output;
 P = Power; — = Not Used; TTL = TTL input; ST = Schmitt Trigger input

- Note 1:** The output is only available by the peripheral operation.
Note 2: Open drain input/output pin. Pin forced to input upon any device RESET.

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TABLE 3-1: PINOUT DESCRIPTIONS (CONTINUED)

Name	PIC17C75X			PIC17C76X		I/O/P Type	Buffer Type	Description
	DIP No.	PLCC No.	TQFP No.	PLCC No.	QFP No.			
RG0/AN3	32	34	24	42	30	I/O	ST	PORTG is a bi-directional I/O Port. RG0 can also be analog input 3. RG1 can also be analog input 2. RG2 can also be analog input 1, or the ground reference voltage. RG3 can also be analog input 0, or the positive reference voltage. RG4 can also be the Capture3 input pin. RG5 can also be the PWM3 output pin. RG6 can also be selected as the USART2 (SCI) Asynchronous Receive or USART2 (SCI) Synchronous Data. RG7 can also be selected as the USART2 (SCI) Asynchronous Transmit or USART2 (SCI) Synchronous Clock.
RG1/AN2	31	33	23	41	29	I/O	ST	
RG2/AN1/VREF-	30	32	22	40	28	I/O	ST	
RG3/AN0/VREF+	29	31	21	39	27	I/O	ST	
RG4/CAP3	35	38	27	46	33	I/O	ST	
RG5/PWM3	36	39	28	47	34	I/O	ST	
RG6/RX2/DT2	38	41	30	49	36	I/O	ST	
RG7/TX2/CK2	37	40	29	48	35	I/O	ST	
RH0	—	—	—	10	79	I/O	ST	PORTH is a bi-directional I/O Port. PORTH is only available on the PIC17C76X devices. RH4 can also be analog input 12. RH5 can also be analog input 13. RH6 can also be analog input 14. RH7 can also be analog input 15.
RH1	—	—	—	11	80	I/O	ST	
RH2	—	—	—	12	1	I/O	ST	
RH3	—	—	—	13	2	I/O	ST	
RH4/AN12	—	—	—	31	19	I/O	ST	
RH5/AN13	—	—	—	32	20	I/O	ST	
RH6/AN14	—	—	—	33	21	I/O	ST	
RH7/AN15	—	—	—	34	22	I/O	ST	
RJ0	—	—	—	52	39	I/O	ST	PORTJ is a bi-directional I/O Port. PORTJ is only available on the PIC17C76X devices.
RJ1	—	—	—	53	40	I/O	ST	
RJ2	—	—	—	54	41	I/O	ST	
RJ3	—	—	—	55	42	I/O	ST	
RJ4	—	—	—	73	59	I/O	ST	
RJ5	—	—	—	74	60	I/O	ST	
RJ6	—	—	—	75	61	I/O	ST	
RJ7	—	—	—	76	62	I/O	ST	
TEST	16	17	8	21	10	I	ST	Test mode selection control input. Always tie to Vss for normal operation.
VSS	17, 33, 49, 64	19, 36, 53, 68	9, 25, 41, 56	23, 44, 65, 84	11, 31, 51, 70	P		Ground reference for logic and I/O pins.
VDD	1, 18, 34, 46	2, 20, 37, 49	10, 26, 38, 57	24, 45, 61, 2	12, 32, 48, 71	P		Positive supply for logic and I/O pins.
AVSS	28	30	20	38	26	P		Ground reference for A/D converter. This pin MUST be at the same potential as Vss.
AVDD	27	29	19	37	25	P		Positive supply for A/D converter. This pin MUST be at the same potential as VDD.
NC	—	1, 18, 35, 52	—	1, 22, 43, 64	—			No Connect. Leave these pins unconnected.

Legend: I = Input only; O = Output only; I/O = Input/Output;
P = Power; — = Not Used; TTL = TTL input; ST = Schmitt Trigger input

Note 1: The output is only available by the peripheral operation.
Note 2: Open drain input/output pin. Pin forced to input upon any device RESET.

4.0 ON-CHIP OSCILLATOR CIRCUIT

The internal oscillator circuit is used to generate the device clock. Four device clock periods generate an internal instruction clock (T_{CY}).

There are four modes that the oscillator can operate in. They are selected by the device configuration bits during device programming. These modes are:

- LF Low Frequency ($F_{OSC} \leq 2$ MHz)
- XT Standard Crystal/Resonator Frequency (2 MHz $\leq F_{OSC} \leq 33$ MHz)
- EC External Clock Input (Default oscillator configuration)
- RC External Resistor/Capacitor ($F_{OSC} \leq 4$ MHz)

There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 96 ms (nominal) on POR and BOR. The PWRT is designed to keep the part in RESET while the power supply stabilizes. With these two timers on-chip, most applications need no external RESET circuitry.

SLEEP mode is designed to offer a very low current power-down mode. The user can wake from SLEEP through external RESET, Watchdog Timer Reset, or through an interrupt.

Several oscillator options are made available to allow the part to better fit the application. The RC oscillator option saves system cost while the LF crystal option saves power. Configuration bits are used to select various options.

4.1 Oscillator Configurations

4.1.1 OSCILLATOR TYPES

The PIC17CXXX can be operated in four different oscillator modes. The user can program two configuration bits ($F_{OSC1}:F_{OSC0}$) to select one of these four modes:

- LF Low Power Crystal
- XT Crystal/Resonator
- EC External Clock Input
- RC Resistor/Capacitor

The main difference between the LF and XT modes is the gain of the internal inverter of the oscillator circuit, which allows the different frequency ranges.

For more details on the device configuration bits, see Section 17.0.

4.1.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT or LF modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 4-2). The PIC17CXXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

For frequencies above 24 MHz, it is common for the crystal to be an overtone mode crystal. Use of overtone mode crystals require a tank circuit to attenuate the gain at the fundamental frequency. Figure 4-3 shows an example circuit.

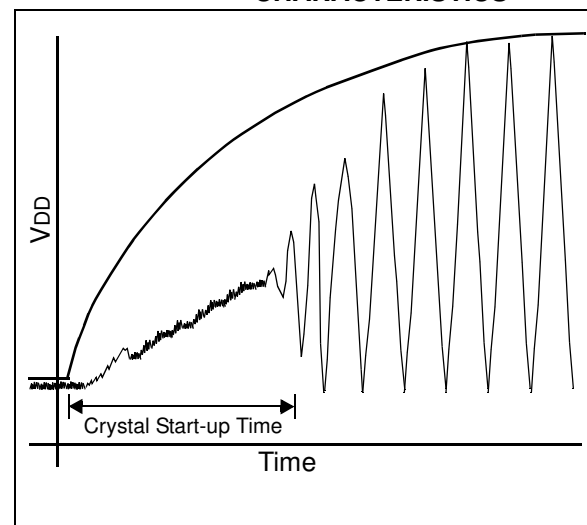
4.1.3 OSCILLATOR/RESONATOR START-UP

As the device voltage increases from V_{SS} , the oscillator will start its oscillations. The time required for the oscillator to start oscillating depends on many factors. These include:

- Crystal/resonator frequency
- Capacitor values used (C1 and C2)
- Device V_{DD} rise time
- System temperature
- Series resistor value (and type) if used
- Oscillator mode selection of device (which selects the gain of the internal oscillator inverter)

Figure 4-1 shows an example of a typical oscillator/resonator start-up. The peak-to-peak voltage of the oscillator waveform can be quite low (less than 50% of device V_{DD}) when the waveform is centered at $V_{DD}/2$ (refer to parameter #D033 and parameter #D043 in the electrical specification section).

FIGURE 4-1: OSCILLATOR/RESONATOR START-UP CHARACTERISTICS



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FIGURE 4-2: CRYSTAL OR CERAMIC RESONATOR OPERATION (XT OR LF OSC CONFIGURATION)

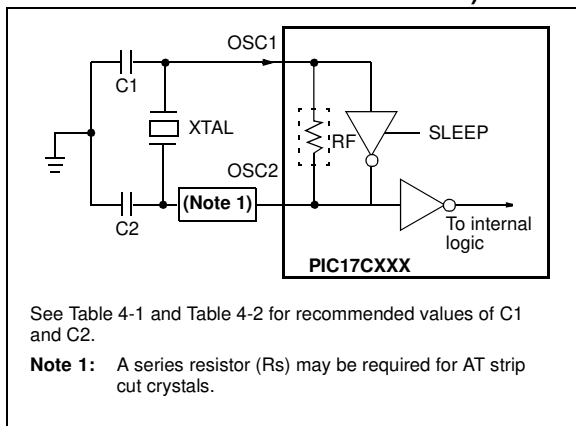


FIGURE 4-3: CRYSTAL OPERATION, OVERTONE CRYSTALS (XT OSC CONFIGURATION)

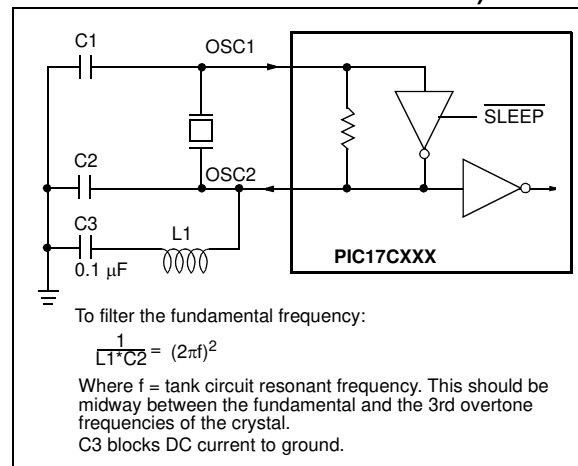


TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Oscillator Type	Resonator Frequency	Capacitor Range C1 = C2 ⁽¹⁾
LF	455 kHz	15 - 68 pF
	2.0 MHz	10 - 33 pF
XT	4.0 MHz	22 - 68 pF
	8.0 MHz	33 - 100 pF
	16.0 MHz	33 - 100 pF

Higher capacitance increases the stability of the oscillator, but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

Note 1: These values include all board capacitances on this pin. Actual capacitor value depends on board capacitance.

Resonators Used:

455 kHz	Panasonic EFO-A455K04B	± 0.3%
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%

Resonators used did not have built-in capacitors.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Freq	C1 ⁽²⁾	C2 ⁽²⁾
LF	32 kHz	100-150 pF	100-150 pF
	1 MHz	10-68 pF	10-68 pF
	2 MHz	10-68 pF	10-68 pF
XT	2 MHz	47-100 pF	47-100 pF
	4 MHz	15-68 pF	15-68 pF
	8 MHz	15-47 pF	15-47 pF
	16 MHz	15-47 pF	15-47 pF
	24 MHz ⁽¹⁾	15-47 pF	15-47 pF
	32 MHz ⁽¹⁾	10-47 pF	10-47 pF

Higher capacitance increases the stability of the oscillator, but also increases the start-up time and the oscillator current. These values are for design guidance only. RS may be required in XT mode to avoid overdriving the crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values for external components.

Note 1: Overtone crystals are used at 24 MHz and higher. The circuit in Figure 4-3 should be used to select the desired harmonic frequency.

2: These values include all board capacitances on this pin. Actual capacitor value depends on board capacitance.

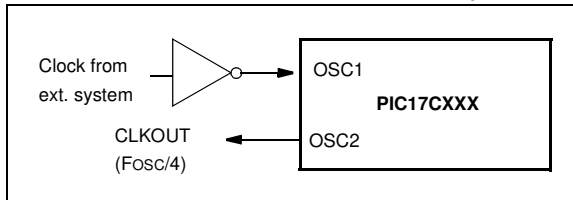
Crystals Used:

32.768 kHz	Epson C-001R32.768K-A	± 20 PPM
1.0 MHz	ECS-10-13-1	± 50 PPM
2.0 MHz	ECS-20-20-1	± 50 PPM
4.0 MHz	ECS-40-20-1	± 50 PPM
8.0 MHz	ECS ECS-80-S-4 ECS-80-18-1	± 50 PPM
16.0 MHz	ECS-160-20-1	± 50 PPM
25 MHz	CTS CTS25M	± 50 PPM
32 MHz	CRYSTEK HF-2	± 50 PPM

4.1.4 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 T_{osc}).

FIGURE 4-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



4.1.5 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used, or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with series resonance, or one with parallel resonance.

Figure 4-5 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 k Ω resistor provides the negative feedback for stability. The 10 k Ω potentiometer biases the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 4-5: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

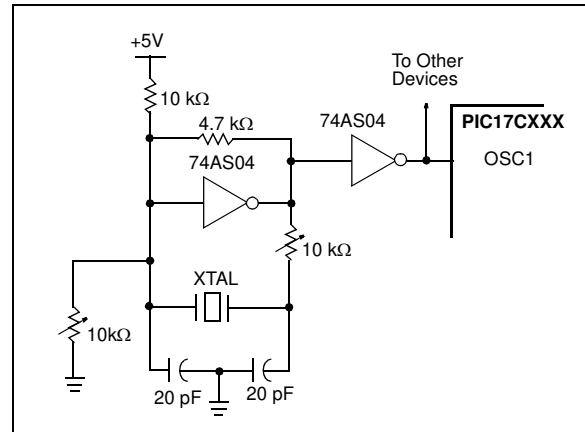
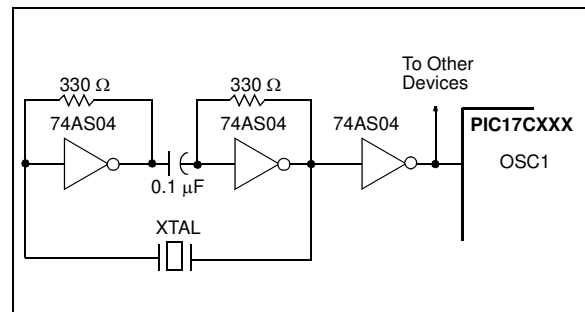


Figure 4-6 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 4-6: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



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4.1.6 RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) and capacitor (C_{EXT}) values, and the operating temperature. In addition to this, oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect oscillation frequency, especially for low C_{EXT} values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 4-7 shows how the R/C combination is connected to the PIC17CXXX. For R_{EXT} values below 2.2 k Ω , the oscillator operation may become unstable, or stop completely. For very high R_{EXT} values (e.g. 1 M Ω), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep R_{EXT} between 3 k Ω and 100 k Ω .

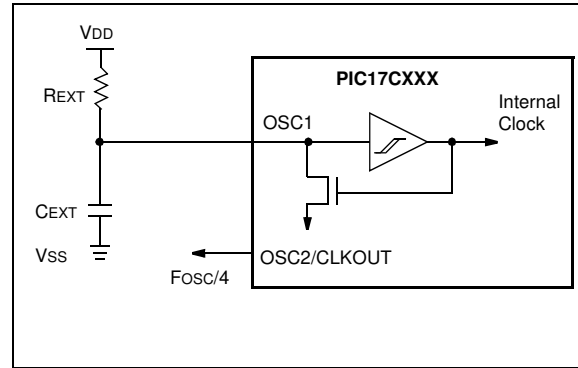
Although the oscillator will operate with no external capacitor ($C_{EXT} = 0$ pF), we recommend using values above 20 pF for noise and stability reasons. With little or no external capacitance, oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 21.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 21.0 for variation of oscillator frequency due to V_{DD} for given R_{EXT}/C_{EXT} values, as well as frequency variation due to operating temperature for given R, C, and V_{DD} values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin and can be used for test purposes or to synchronize other logic (see Figure 4-8 for waveform).

FIGURE 4-7: RC OSCILLATOR MODE



4.1.6.1 RC Start-up

As the device voltage increases, the RC will immediately start its oscillations once the pin voltage levels meet the input threshold specifications (parameter #D032 and parameter #D042 in the electrical specification section). The time required for the RC to start oscillating depends on many factors. These include:

- Resistor value used
- Capacitor value used
- Device V_{DD} rise time
- System temperature

4.2 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1 and the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 4-8.

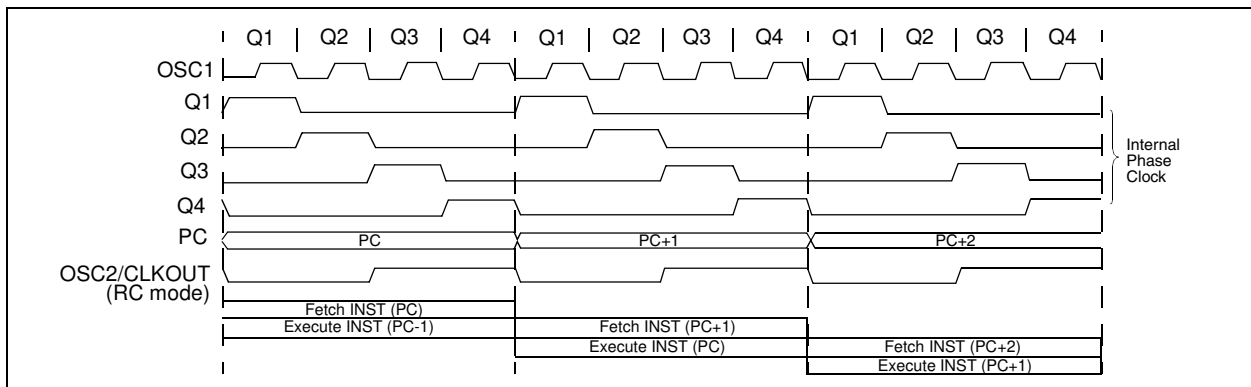
4.3 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle, while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. GOTO), then two cycles are required to complete the instruction (Example 4-1).

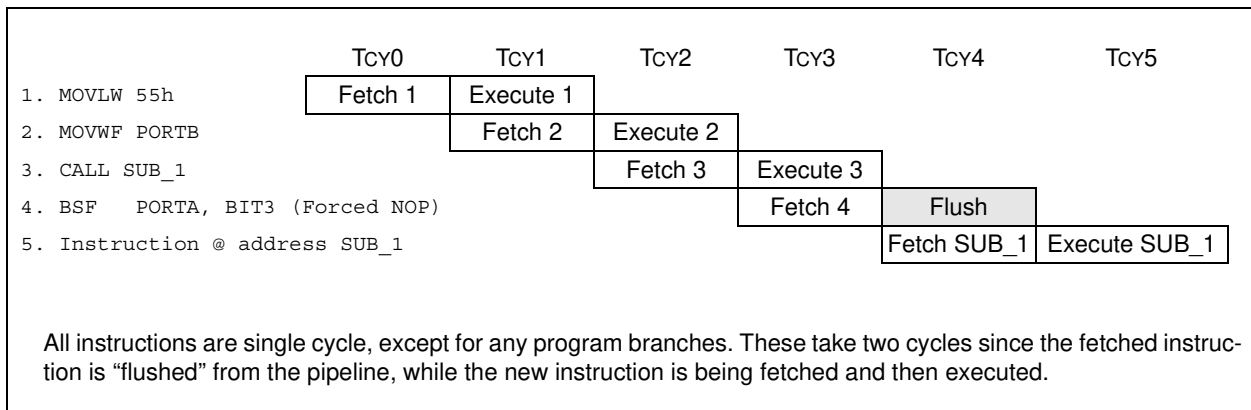
A fetch cycle begins with the program counter incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 4-8: CLOCK/INSTRUCTION CYCLE



EXAMPLE 4-1: INSTRUCTION PIPELINE FLOW



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NOTES:

5.0 RESET

The PIC17CXXX differentiates between various kinds of RESET:

- Power-on Reset (POR)
- Brown-out Reset
- MCLR Reset
- WDT Reset

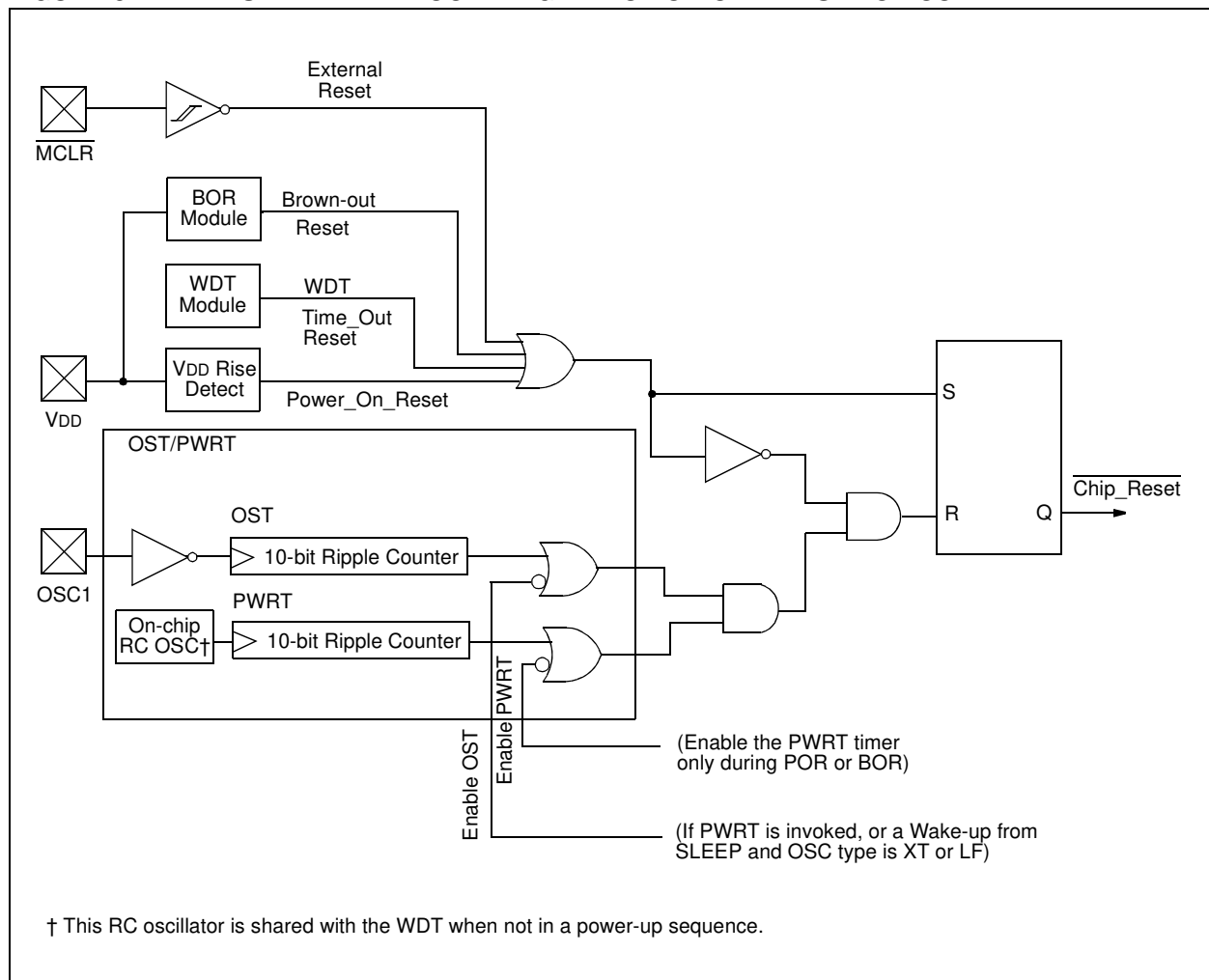
Some registers are not affected in any RESET condition, their status is unknown on POR and unchanged in any other RESET. Most other registers are forced to a "RESET state". The TO and PD bits are set or cleared differently in different RESET situations, as indicated in Table 5-3. These bits, in conjunction with the POR and BOR bits, are used in software to determine the nature of the RESET. See Table 5-4 for a full description of the RESET states of all registers.

When the device enters the "RESET state", the Data Direction registers (DDR) are forced set, which will make the I/O hi-impedance inputs. The RESET state of some peripheral modules may force the I/O to other operations, such as analog inputs or the system bus.

Note: While the device is in a RESET state, the internal phase clock is held in the Q1 state. Any processor mode that allows external execution will force the RE0/ALE pin as a low output and the RE1/OE and RE2/WR pins as high outputs.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



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5.1 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

5.1.1 POWER-ON RESET (POR)

The Power-on Reset circuit holds the device in RESET until VDD is above the trip point (in the range of 1.4V - 2.3V). The devices produce an internal RESET for both rising and falling VDD. To take advantage of the POR, just tie the MCLR/VPP pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A minimum rise time for VDD is required. See Electrical Specifications for details.

Figure 5-2 and Figure 5-3 show two possible POR circuits.

FIGURE 5-2: USING ON-CHIP POR

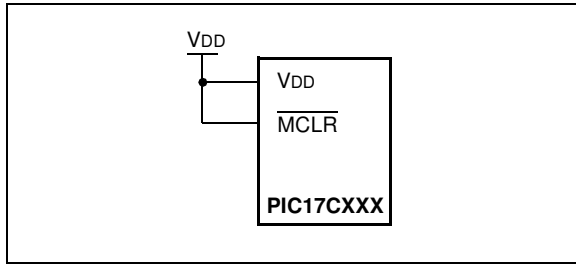
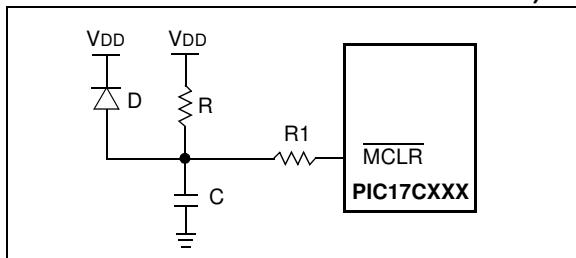


FIGURE 5-3: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- Note 1:** An external Power-on Reset circuit is required only if VDD power-up time is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
- Note 2:** $R < 40\text{ k}\Omega$ is recommended to ensure that the voltage drop across R does not exceed 0.2V (max. leakage current spec. on the MCLR/VPP pin is 5 μA). A larger voltage drop will degrade VIH level on the MCLR/VPP pin.
- Note 3:** $R1 = 100\Omega$ to 1 k Ω will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

5.1.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 96 ms time-out (nominal) on power-up. This occurs from the rising edge of the internal POR signal if VDD and MCLR are tied, or after the first rising edge of MCLR (detected high). The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. In most cases, the PWRT delay allows VDD to rise to an acceptable level.

The power-up time delay will vary from chip to chip and with VDD and temperature. See DC parameters for details.

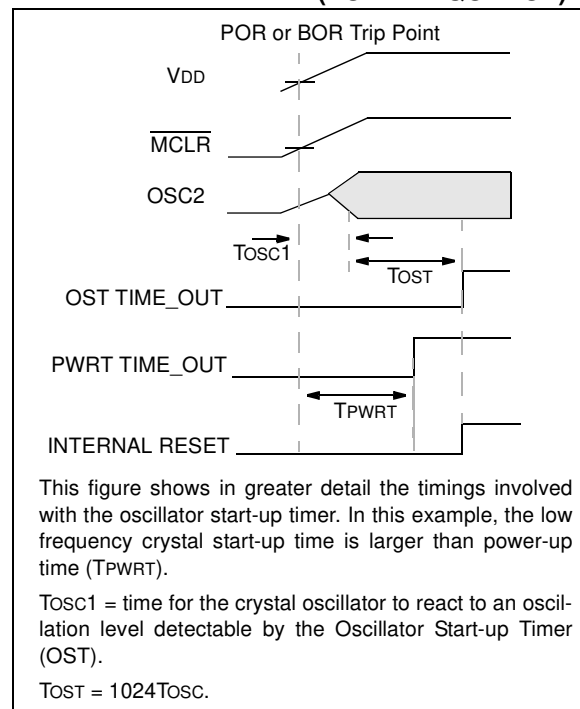
5.1.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle ($1024T_{osc}$) delay whenever the PWRT is invoked, or a wake-up from SLEEP event occurs in XT or LF mode. The PWRT and OST operate in parallel.

The OST counts the oscillator pulses on the OSC1/CLKIN pin. The counter only starts incrementing after the amplitude of the signal reaches the oscillator input thresholds. This delay allows the crystal oscillator or resonator to stabilize before the device exits RESET. The length of the time-out is a function of the crystal/resonator frequency.

Figure 5-4 shows the operation of the OST circuit. In this figure, the oscillator is of such a low frequency that although enabled simultaneously, the OST does not time-out until after the Power-up Timer time-out.

FIGURE 5-4: OSCILLATOR START-UP TIME (LOW FREQUENCY)



5.1.4 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: First, the internal POR signal goes high when the POR trip point is reached. If $\overline{\text{MCLR}}$ is high, then both the OST and PWRT timers start. In general, the PWRT time-out is longer, except with low frequency crystals/resonators. The total time-out also varies based on oscillator configuration. Table 5-1 shows the times that are associated with the oscillator configuration. Figure 5-5 and Figure 5-6 display these time-out sequences.

If the device voltage is not within electrical specification at the end of a time-out, the $\overline{\text{MCLR}}/\text{VPP}$ pin must be held low until the voltage is within the device specification. The use of an external RC delay is sufficient for many of these applications.

The time-out sequence begins from the first rising edge of $\overline{\text{MCLR}}$.

Table 5-3 shows the RESET conditions for some special registers, while Table 5-4 shows the initialization conditions for all the registers.

TABLE 5-1: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	POR, BOR	Wake-up from SLEEP	$\overline{\text{MCLR}}$ Reset
XT, LF	Greater of: 96 ms or $1024T_{\text{osc}}$	$1024T_{\text{osc}}$	—
EC, RC	Greater of: 96 ms or $1024T_{\text{osc}}$	—	—

TABLE 5-2: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}^{(1)}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Event
0	0	1	1	Power-on Reset
1	1	1	0	$\overline{\text{MCLR}}$ Reset during SLEEP or interrupt wake-up from SLEEP
1	1	0	1	WDT Reset during normal operation
1	1	0	0	WDT Wake-up during SLEEP
1	1	1	1	$\overline{\text{MCLR}}$ Reset during normal operation
1	0	1	1	Brown-out Reset
0	0	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	0	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
x	x	1	1	CLRWDT instruction executed

Note 1: When BODEN is enabled, else the $\overline{\text{BOR}}$ status bit is unknown.

TABLE 5-3: RESET CONDITION FOR THE PROGRAM COUNTER AND THE CPUSTA REGISTER

Event	PCH:PCL	CPUSTA ⁽⁴⁾	OST Active
Power-on Reset	0000h	--11 1100	Yes
Brown-out Reset	0000h	--11 1110	Yes
$\overline{\text{MCLR}}$ Reset during normal operation	0000h	--11 1111	No
$\overline{\text{MCLR}}$ Reset during SLEEP	0000h	--11 1011	Yes ⁽²⁾
WDT Reset during normal operation	0000h	--11 0111	No
WDT Reset during SLEEP ⁽³⁾	0000h	--11 0011	Yes ⁽²⁾
Interrupt Wake-up from SLEEP	GLINTD is set	PC + 1	Yes ⁽²⁾
	GLINTD is clear	PC + 1 ⁽¹⁾	Yes ⁽²⁾

Legend: u = unchanged, x = unknown, - = unimplemented, read as '0'

Note 1: On wake-up, this instruction is executed. The instruction at the appropriate interrupt vector is fetched and then executed.

2: The OST is only active (on wake-up) when the oscillator is configured for XT or LF modes.

3: The Program Counter = 0; that is, the device branches to the RESET vector and places SFRs in WDT Reset states. This is different from the mid-range devices.

4: When BODEN is enabled, else the $\overline{\text{BOR}}$ status bit is unknown.